

NOT RECOMMENDED FOR NEW DESIGN USE DMN2024U



DMG6968U

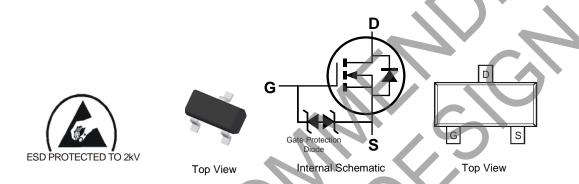
N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
 - 25mΩ @ V_{GS} = 4.5V
 - 29mΩ @ V_{GS} = 2.5V
 - $36m\Omega$ @ $V_{GS} = 1.8V$
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 3
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (Approximate)



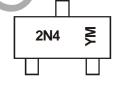
Ordering Information (Note 5)

Part Number	Compliance	Case	Packaging
DMG6968U-7	Standard	SOT23	3000/Tape & Reel
DMG6968UQ-7	Automotive	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally
 the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



2N4 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	2009		2017	2018	2019	2020	2021	2022	2023	2024	2025	2026
Code	W		Е	F	G	Н		J	K	L	М	N
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



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DMG6968U

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characte	eristic		Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage		V _{GSS}	±12	V	
Continuous Drain Current (Note 6)	T _A = +25°C T _A = +70°C	I _D	6.5 5.2	А	
Pulsed Drain Current	•		I _{DM}	30	Α

Thermal Characteristics

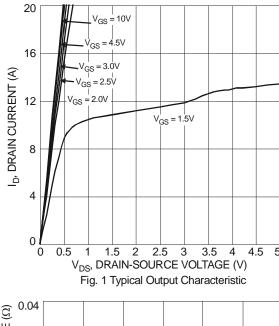
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	1.3	W
Thermal Resistance, Junction to Ambient @ T _A = +25°C	$R_{\theta JA}$	157	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

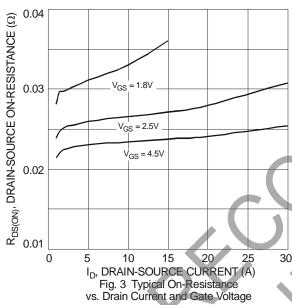
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

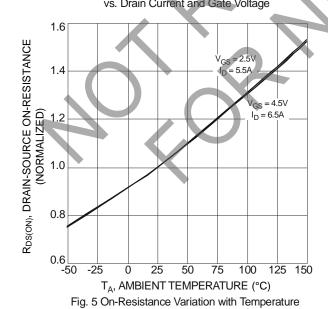
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)	OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20			V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}		1	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$		
Gate-Source Leakage	I _{GSS}	Į		±10	μΑ	$V_{GS} = \pm 10V, V_{DS} = 0V$		
Gate-Source Breakdown Voltage	BV _{SGS}	±12	3 –		V	$V_{DS} = 0V, I_{G} = \pm 250 \mu A$		
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage	$V_{GS(TH)}$	0.5		0.9	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$		
			21	25		$V_{GS} = 4.5V, I_D = 6.5A$		
Static Drain-Source On-Resistance	R _{DS(ON)}		23	29	mΩ	$V_{GS} = 2.5V, I_D = 5.5A$		
			28	36		$V_{GS} = 1.8V, I_D = 3.5A$		
Forward Transfer Admittance	Y _{fs}		8	_	S	$V_{DS} = 10V, I_{D} = 5A$		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C _{iss}		151		pF			
Output Capacitance	Coss		91		pF	$V_{DS} = 10V, V_{GS} = 0V$ f = 1.0MHz		
Reverse Transfer Capacitance	Crss		32		pF	1 - 1.000112		
Total Gate Charge	Qg	_	8.5	_	nC			
Gate-Source Charge	Q_gs	_	1.6		nC	$V_{GS} = 4.5V, V_{DS} = 10V, I_D = 6.5A$		
Gate-Drain Charge	Q_{gd}	_	2.8		nC			
Turn-On Delay Time	t _{D(ON)}	_	54		ns			
Turn-On Rise Time	t _R		66		ns	$V_{DD} = 10V, V_{GS} = 4.5V,$		
Turn-Off Delay Time	t _{D(OFF)}		613		ns	$R_L = 10\Omega$, $R_G = 6\Omega$, $I_D = 1A$		
Turn-Off Fall Time	t _F	_	205		ns			

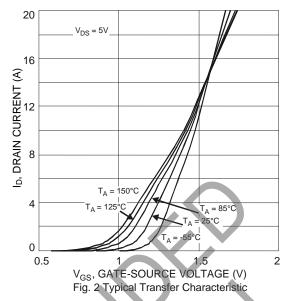
Notes:

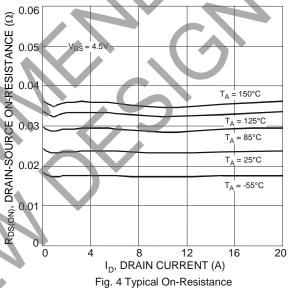
- 6. Device mounted on FR-4 substrate PC board, 2oz. copper, with thermal vias to bottom layer 1 inch square copper plate.7. Short duration pulse test used to minimize self-heating effect.8. Guaranteed by design. Not subject to production testing.











0.06 0.05 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (Ω) 0.04 $V_{GS} = 2.5 V$ $I_D = 5.5A$ 0.03 $V_{GS} = 4.5V$ $I_{D} = 6.5A$ 0.02 0.01 -25 25 50 75 100 125 150 -50 T_A, AMBIENT TEMPERATURE (°C) Fig. 6 On-Resistance Variation with Temperature

vs. Drain Current and Temperature



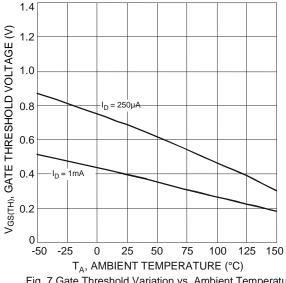
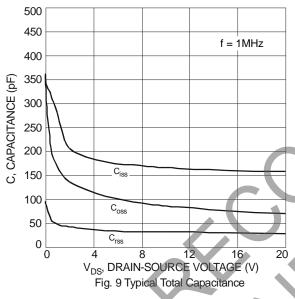
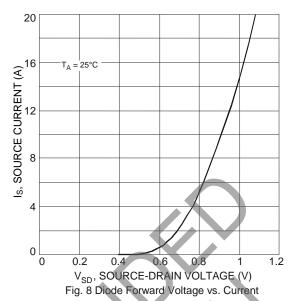
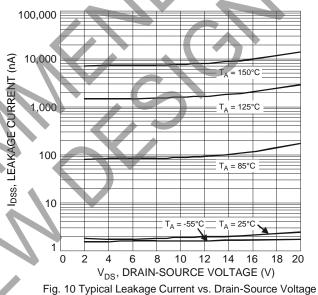


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







r(t), TRANSIENT THERMAL RESISTANCE D = 0.5 D = 0.1 D = 0.05 $\mathsf{R}_{\theta\mathsf{JA}}(t) = \mathsf{r}(t) * \mathsf{R}_{\theta\mathsf{JA}}$ D = 0.02 $R_{\theta JA} = 162^{\circ}C/W$ D = 0.01 D = 0.005 $T_{J} - T_{A} = P * R_{\theta JA}(t)$ Duty Cycle, $D = t_{1}/t_{2}$ 0.001 0.000001 0.00001 0.0001 0.001 0.01 0.1 10 100 1,000 t₁, PULSE DURATION TIME (s)

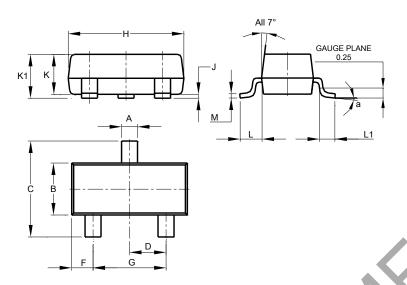
Fig. 11 Transient Thermal Response



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

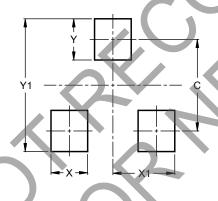


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
U	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
M	0.085	0.150	0.110				
a	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Υ	0.9
Y1	2.9



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